

## SYSTEM AND METHOD FOR REDUCING TEMPERATURE VARIATION DURING BURN IN

### ABSTRACT

Systems and methods for reducing temperature variation during burn-in  
5 testing. In one embodiment, power consumed by an integrated circuit under test  
is measured. An ambient temperature associated with the integrated circuit is  
measured. A desired junction temperature of the integrated circuit is achieved by  
adjusting a body bias voltage of the integrated circuit. By controlling  
temperature of individual integrated circuits, temperature variation during burn-  
10 in testing can be reduced.